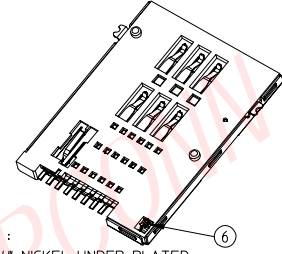
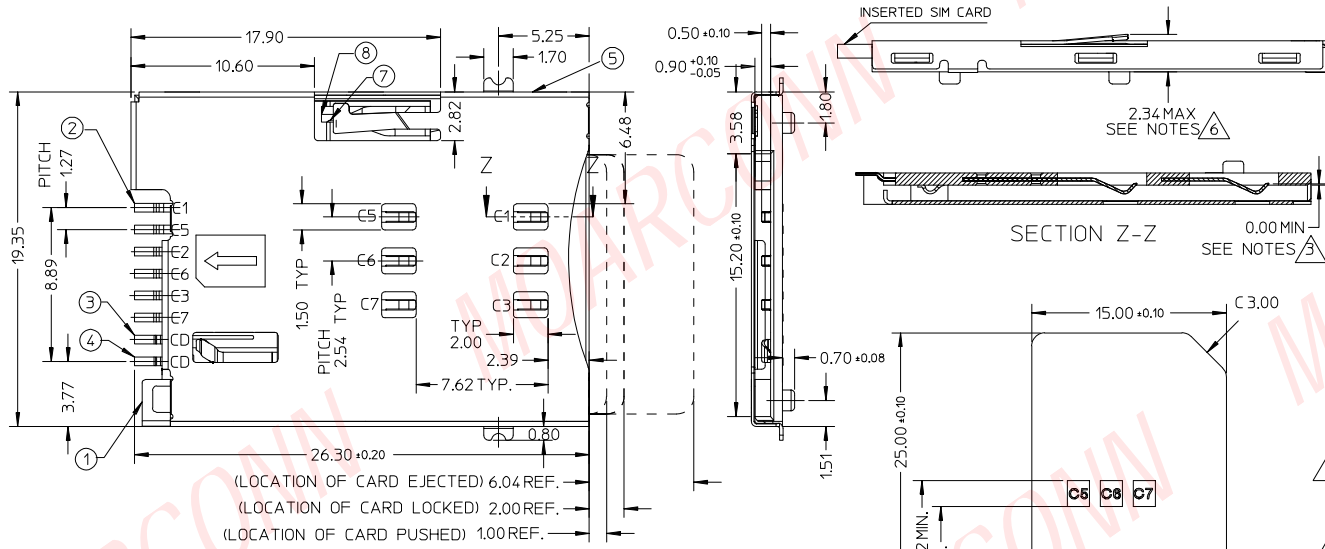
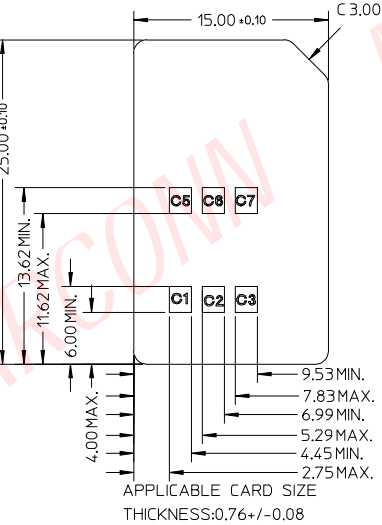


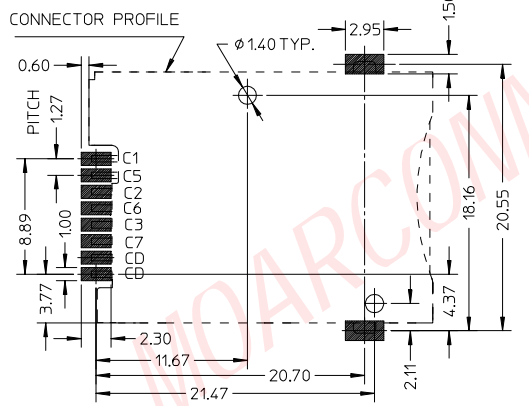
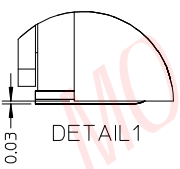
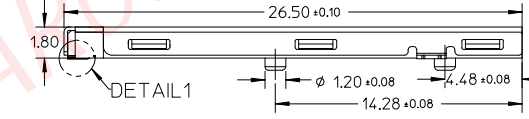
All materials, plating and process meet HF requirements.



- NOTES:
- 1 FINISH:
    - 1-1 TERMINAL :
      - 50~200μm NICKEL UNDER PLATED
      - 15μm GOLD PLATING ON CONTACT AREA
      - 3μm MIN GOLD FLASH ON SOLDERING AREA
    - 1-2 SHELL :
      - 50~200μm NICKEL UNDER PLATED
      - 3μm MIN GOLD FLASH ON SOLDERING AREA
    - 1-3 DETECT PIN :
      - 50~200μm NICKEL UNDER PLATED
      - 3μm MIN GOLD PLATING ON CONTACT AREA
      - 3μm MIN GOLD PLATING ON SOLDERING AREA
  - 2 SOLDER TAIL COPLANARITY: 0.08MM MAX.
  - 3 TERMINAL TIP MUST SINK INTO HOUSING
  - 4 PRODUCT COMPLIANT TO ROHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC
  - 5 DETECT SWITCH: INSERT CARD-ON (NORMAL-OPEN)
  - 6 SPRING RISE UP DURING PUSH-PUSH PERIOD
  - 7 PACKAGE DRAWING: PK-47553-001
  - 8 PRODUCT SPECIFICATION: PS-47553-201



CARD INSERTED		WITHOUT CARD	
NO.	DESCRIPTION	Q'TY	MATERIAL
1	HOUSING	1	HIGH TEMPERATURE THERMOPLASTIC
2	TERMINAL	6	COPPER ALLOY
3	DETECT PIN LOWER	1	COPPER ALLOY
4	DETECT PIN UPPER	1	COPPER ALLOY
5	SHELL	1	STAINLESS STEEL
6	COIL SPRING	1	PIANO WIRE
7	HEART CAM	1	HIGH TEMPERATURE THERMOPLASTIC
8	CAM PIN	1	STAINLESS STEEL



RECOMMENDED PCB LAYOUT  
TOLERANCE +/-0.05MM

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DIMENSIONS INIT: mm  
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.10
X.XX: ±	0.05
X.XXX: ±	0.02
ANGULAR: ±	1°

PRODUCT NAME : <b>SIM Card H1.8 push-push SMT</b>	DRAWING: Zhangli	DATE: 2025.1.4
PRODUCT NO. : SM180-T5153-02-W	CHECK: /	DATE: /
DRAWING NO. : D-SM180-T5153-02-W	APPROVED:	DATE:
SCALE: 1:1	DWG ID: P D	REV.: X0
		PAGE: 1 OF 1

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	-----	NEW RELEASE	Zhangli	2025.1.4
1				
2				
3				